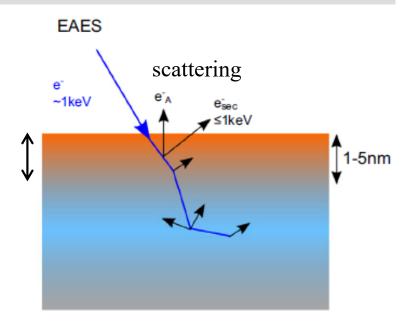
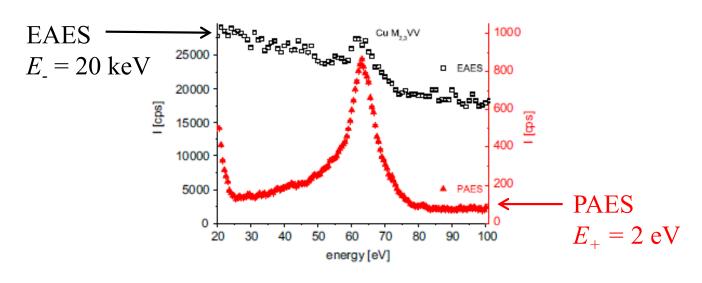


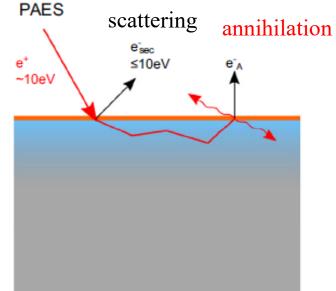
• EAES and PAES comparison

Method	EAES	PAES
Current	$I_{e^-} > \mu A$	$I_{e^+} < pA$
Setup	Simple	Elaborate
Beam energy	\approx keV	$\approx 20 \text{ eV}$
e ⁻ background	High	"Zero"
Information depth	Several at. layers	Topmost at. layer
Auger yield (relative to EAES)	1	> 100
SNR (relative to EAES)	1	> 20



• example pure Cu

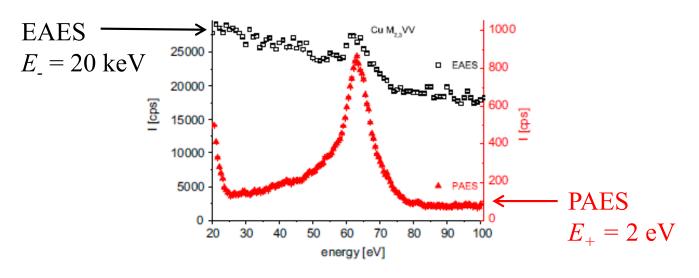




• EAES and PAES comparison

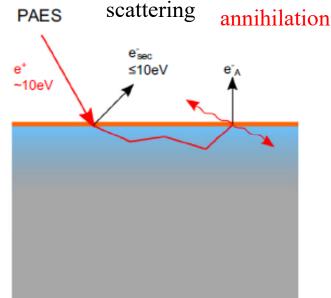
Method	EAES	PAES
Current	$I_{e^-} > \mu A$	$I_{e^+} < pA$
Setup	Simple	Elaborate
Beam energy	\approx keV	$\approx 20 \text{ eV}$
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Auger yield (relative to EAES)	1	> 100
SNR (relative to EAES)	1	> 20

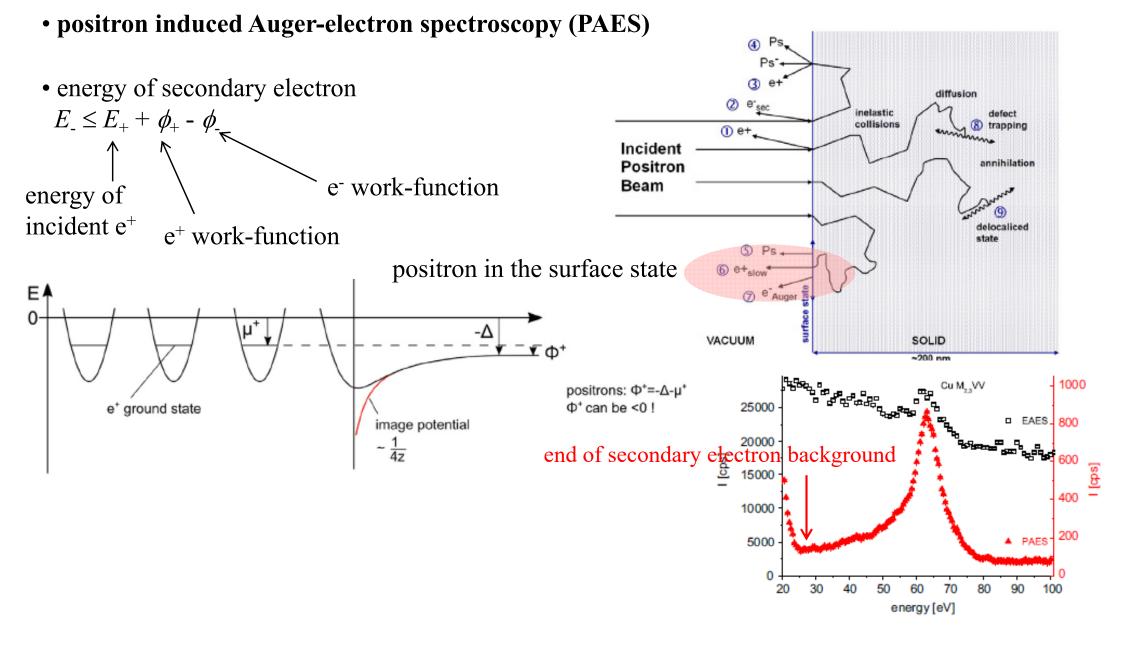
• example pure Cu

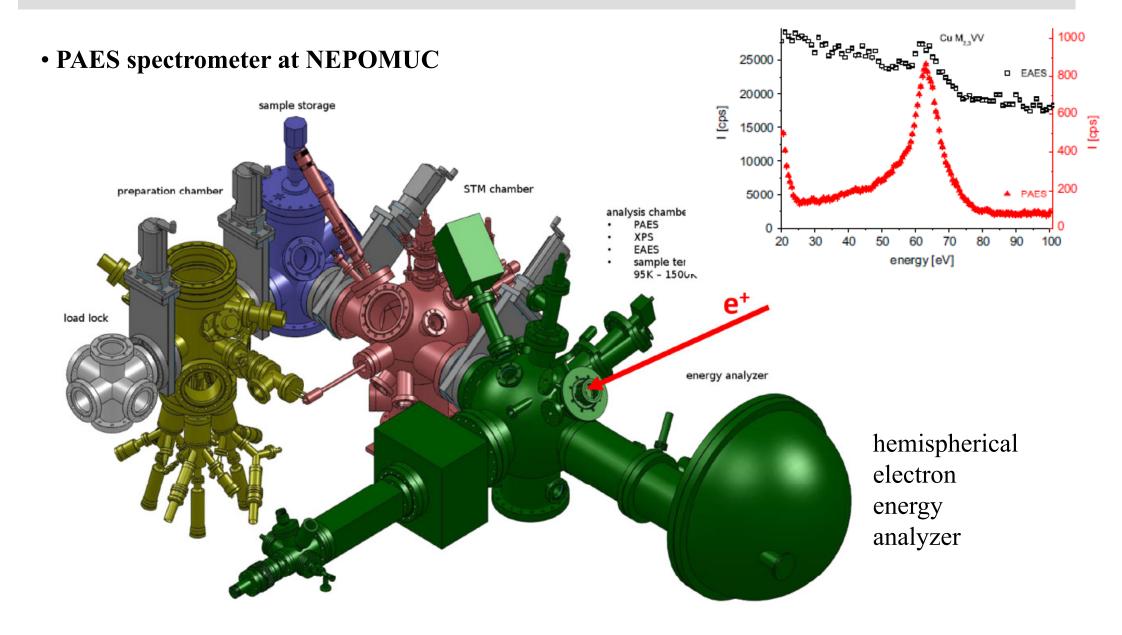


- PAES advantages
- surface sensitivity topmost layer
- Auger electron yield N_A/N_{inc} two orders of magnitude higher compared to EAES
- zero electron background

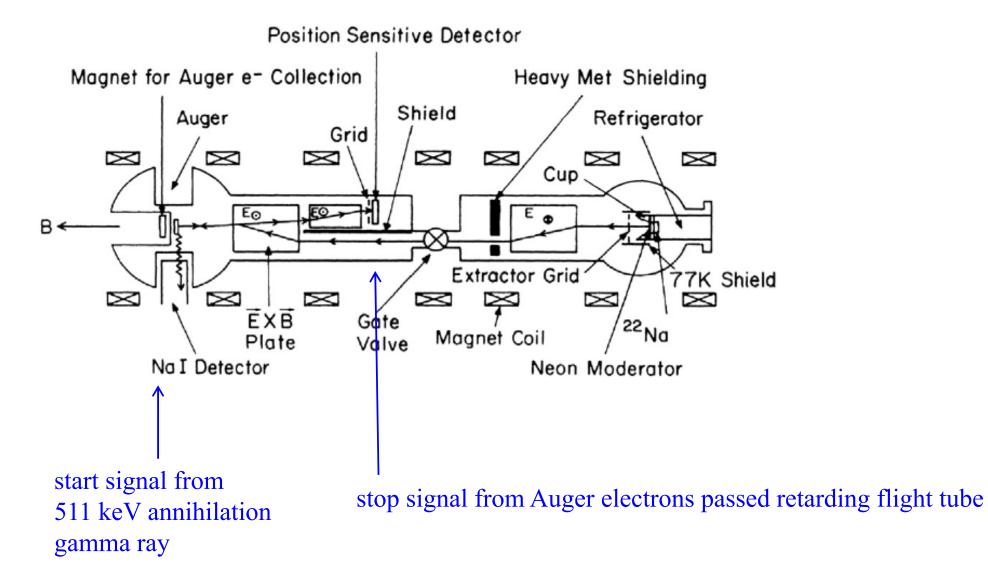
signal-to-noise ratio (SNR) EAES SNR = 1:2 PAES SNR = 10:1

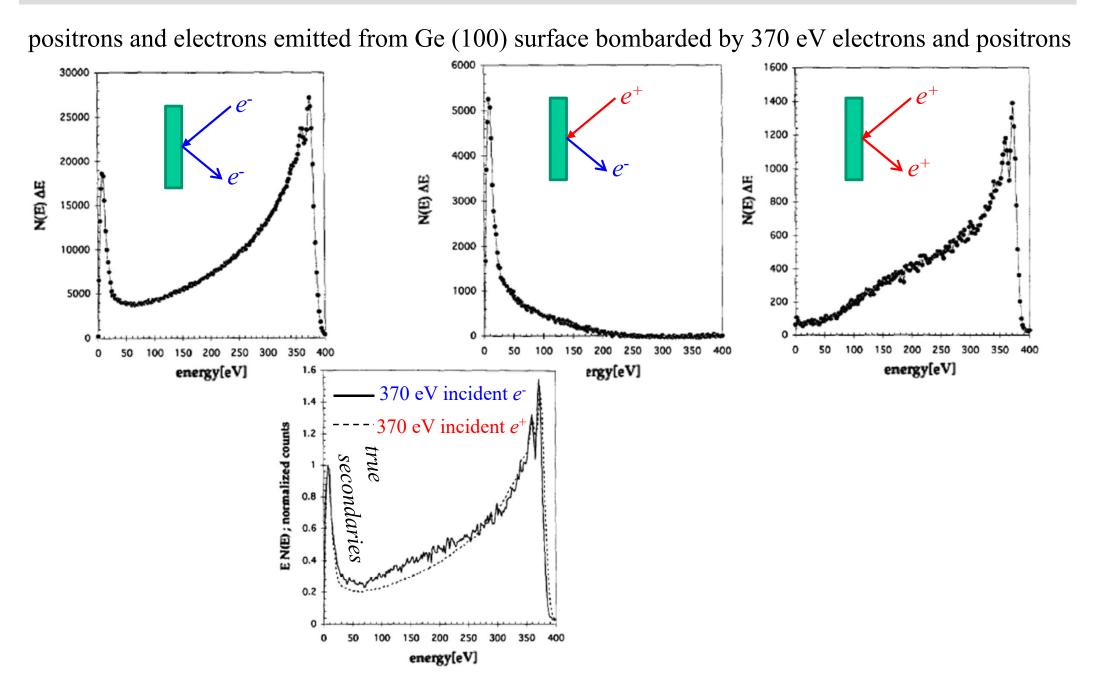




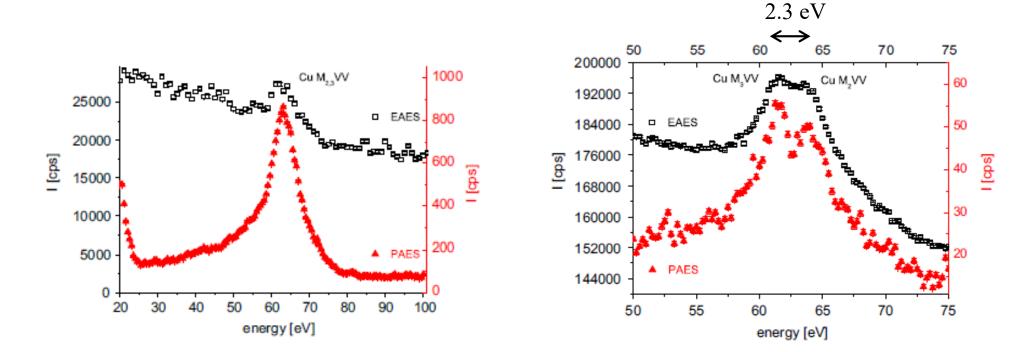


• Time of flight (TOF-PAES) spectrometer at NEPOMUC



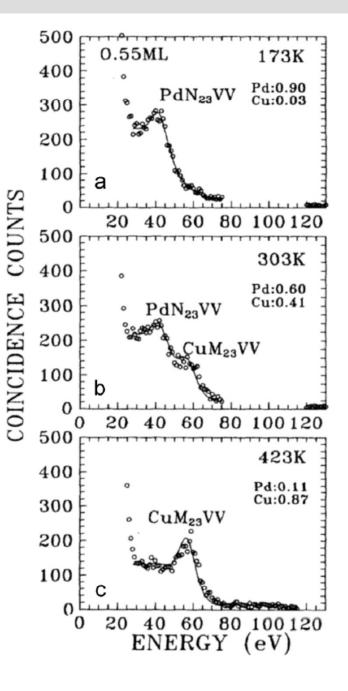


• EAES and PAES on polycrystalline Cu surface



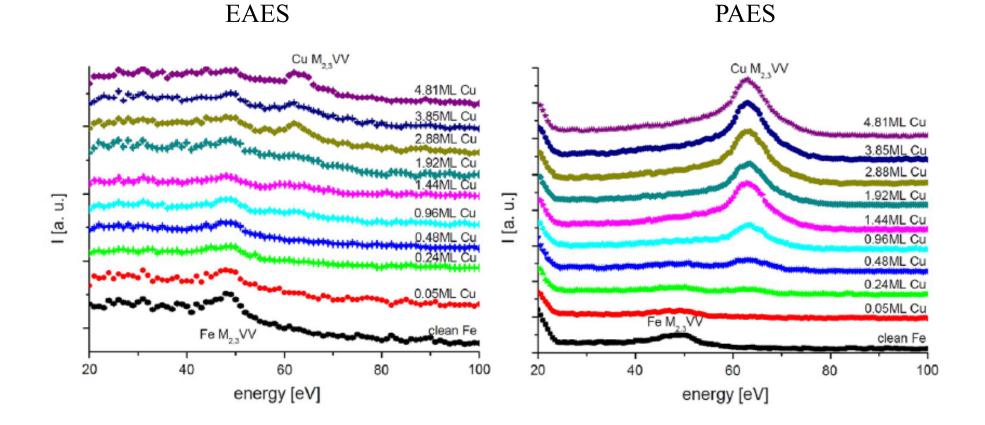
higher resolution Auger-electron analyzer

• PAES on polycrystalline Cu (100) surface covered with 0.55 ML Pd

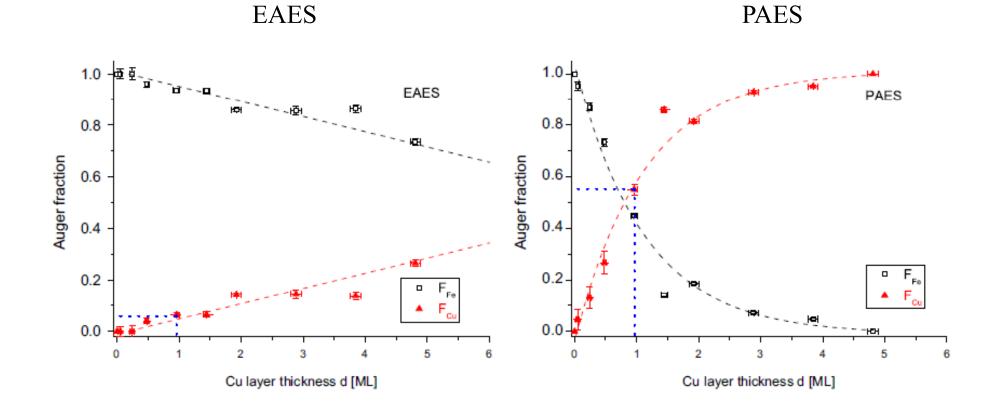


surface alloying of Pd with Cu at 150°C

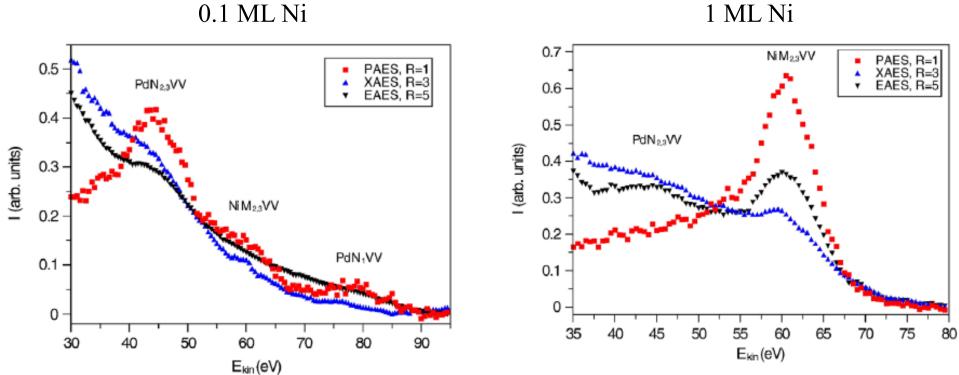
• Fe covered with Cu



• Fe covered with Cu



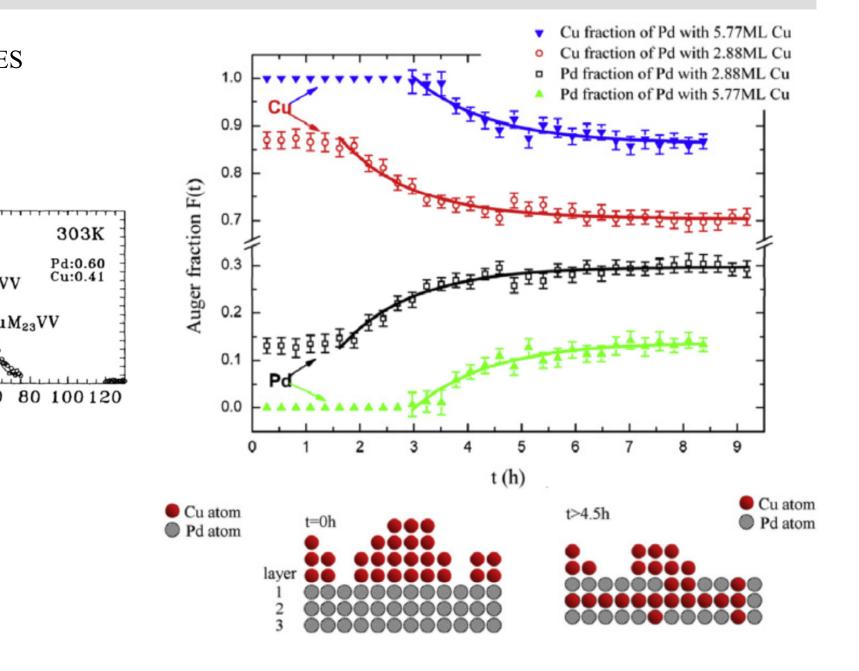
• Pd covered with Ni



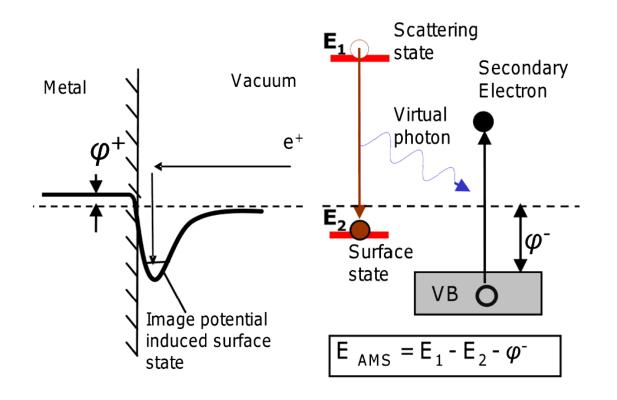
time dependent PAESCu on Pd

PdN₂₃VV

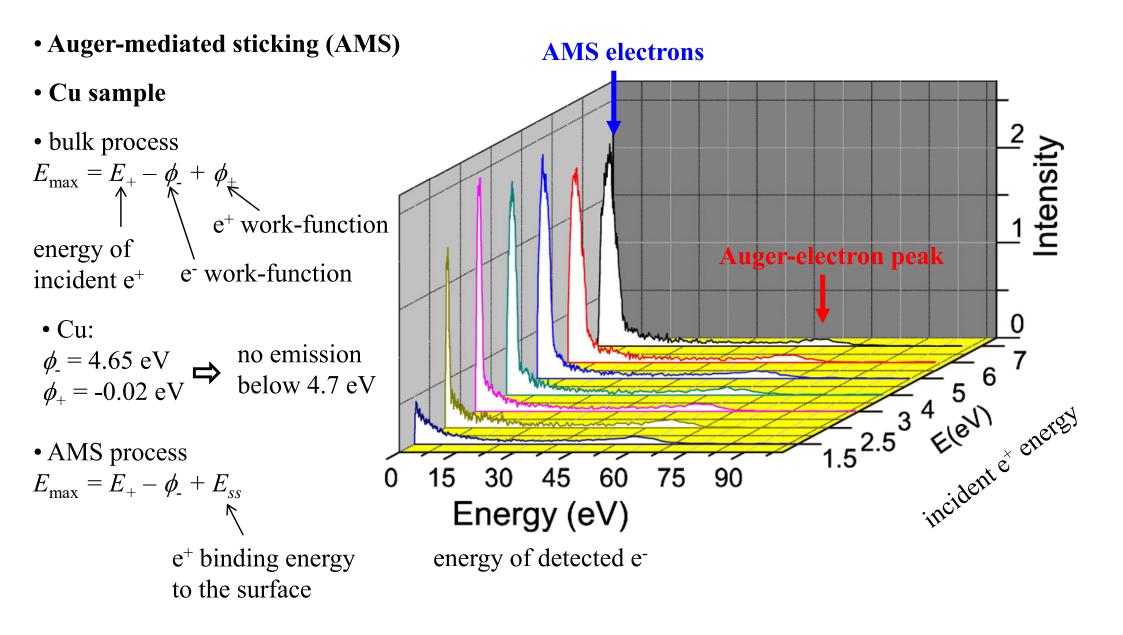
n

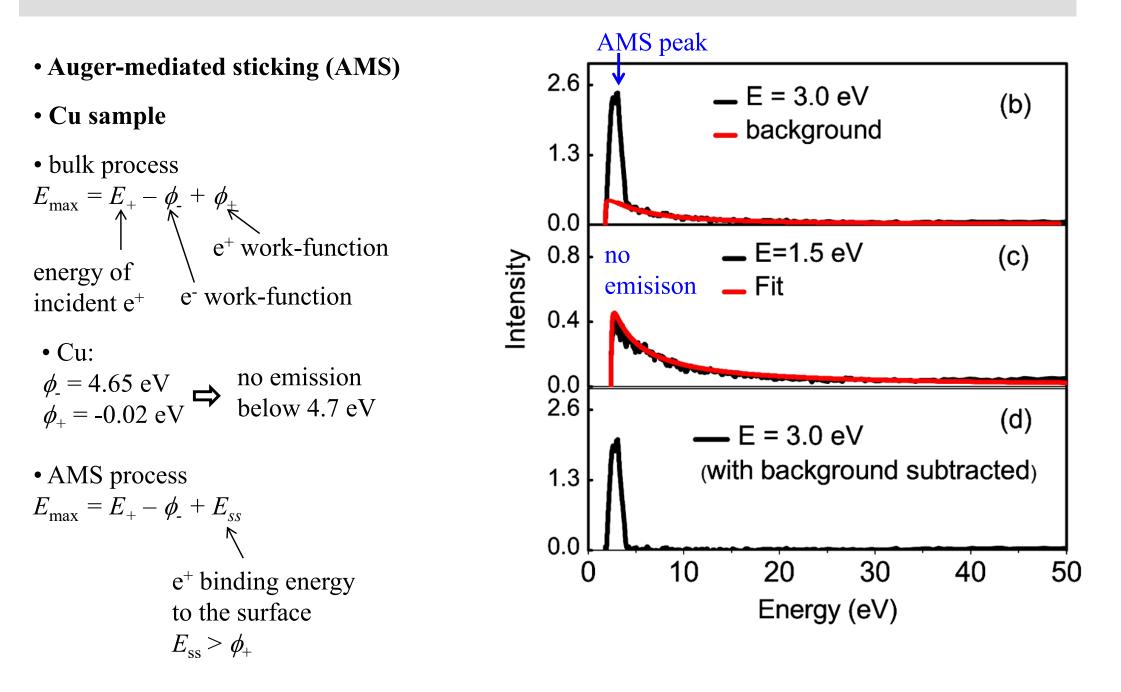


• Auger-mediated sticking (AMS)



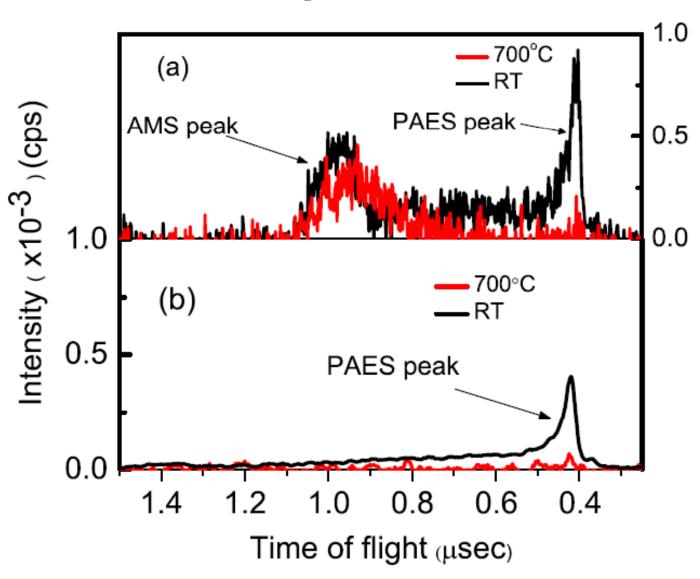
- de Broglie wavelength of 1 keV positron is ≈ 12 Å
- order of magnitude higher than the width of surface potential well





- Auger-mediated sticking (AMS)
- Cu sample
- PAES peak disappears due to thermally activated Ps desorption
- AMS peak remains

Effect of temperature



- Auger-mediated sticking (AMS)
- Cu and Au sample

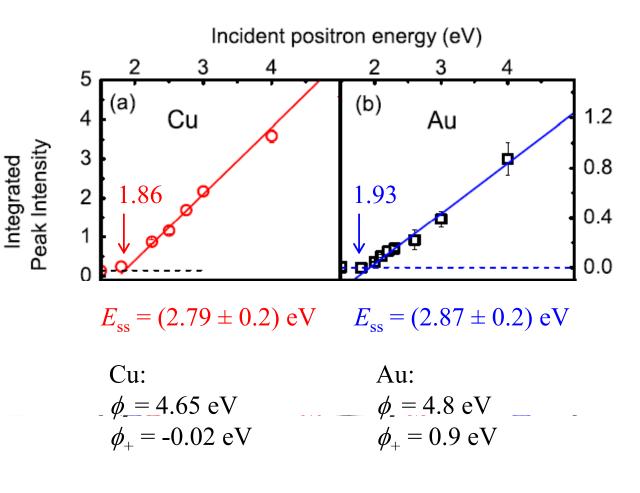
• bulk process $E_{\text{max}} = E_{+} - \phi_{-} + \phi_{+}$ e^{+} work-function energy of incident e^{+} e^{-} work-function • Cu: $\phi_{-} = 4.65 \text{ eV}$ \Rightarrow no emission $\phi_{+} = -0.02 \text{ eV}$ \Rightarrow below 4.7 eV • AMS process $E_{\text{max}} = E_{+} - \phi_{-} + E_{ss}$

e⁺ binding energy

to the surface

 $E_{ss} > \phi_+$

Determination of E_{ss}



- Auger-mediated sticking (AMS)
- Cu and Au sample

• bulk process $E_{\max} = E_{+} - \phi_{\pm} + \phi_{\pm}$ e⁺ work-function energy of e⁻ work-function incident e⁺ • Cu: no emission $\phi_{-} = 4.65 \text{ eV}$ $\Rightarrow \phi_{+} = -0.02 \text{ eV}$ below 4.7 eV • AMS process $E_{\rm max} = E_+ - \phi_- + E_{\rm ss}$ e⁺ binding energy to the surface $E_{\rm ss} > \phi_+$

Determination of E_{ss}

